



Patent

Attorney's Docket No. 015290-426

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of) **BOX AF**
William Frederick BOSCH)
Application No.: 09/607,922) Group Art Unit: 1765
Filed: June 30, 2000) Examiner: L. T. Umez-Eronini
For: SEMICONDUCTOR PROCESSING)
EQUIPMENT HAVING IMPROVED)
PARTICLE PERFORMANCE)

RECEIVED
APR 24 2002
TC 1700

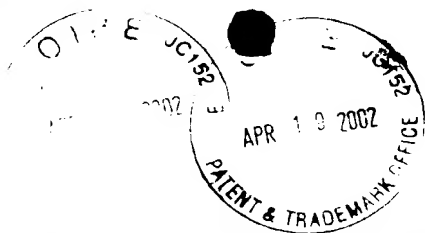
AMENDMENT/REPLY TRANSMITTAL LETTER

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Enclosed is a reply for the above-identified patent application.

- ☐ A Petition for Extension of Time is also enclosed.
- ☐ A Terminal Disclaimer and a check for ☐ \$55.00 (248) ☐ \$110.00 (148) to cover the requisite Government fee are also enclosed.
- ☒ Also enclosed is an Information Disclosure Statement.
- ☐ Small entity status is hereby claimed.
- ☐ Applicant(s) request continued examination under 37 C.F.R. § 1.114 and enclose the ☐ \$370.00 (279) ☐ \$740.00 (179) fee due under 37 C.F.R. § 1.17(e).
 - ☐ Applicant(s) previously submitted __, on __, for which continued examination is requested.
- ☐ Applicant(s) request suspension of action by the Office until at least __, which does not exceed three months from the filing of this RCE, in accordance with 37 C.F.R. § 1.103(c). The required fee under 37 C.F.R. § 1.17(i) is enclosed.
- ☐ A Request for Entry and Consideration of Submission under 37 C.F.R. § 1.129(a) (146/246) is also enclosed.
- ☐ No additional claim fee is required.



7/13/02
44
125/10

Patent
Attorney's Docket No. 015290-426

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)	BOX AF
)	
William Frederick BOSCH)	Group Art Unit: 1765
)	
Application No.: 09/607,922)	Examiner: L. T. Umez-Eronini
)	
Filed: June 30, 2000)	
)	
For: SEMICONDUCTOR PROCESSING)	
EQUIPMENT HAVING IMPROVED)	
PARTICLE PERFORMANCE)	

RECEIVED
APR 24 2002
TC 1700

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Official Action mailed March 5, 2002, please amend the above-identified application as follows.

IN THE CLAIMS:

Please replace Claims 1, 15-18 and 24-29 and add new Claims 31-34 as follows:

- 50b 112
1. (Amended) A method of processing semiconductor substrates and reducing particle contamination during processing of the substrates, the method comprising steps of:
 - (a) placing at least one substrate on a substrate holder in an interior space of a vacuum processing chamber, the processing chamber including at least one ceramic part made of a non-oxide ceramic material and having a machined and/or sintered surface exposed to the interior space, the exposed surface having been treated to reduce particles of